

FIDUCIAL ALIGNMENT MARKS ON MICROELECTRONIC SPRING CONTACTS

ABSTRACT OF THE DISCLOSURE

5 Microelectronic spring contacts with fiducial alignment marks for use on a semiconductor wafer contactor or similar apparatus, and methods for making such marks, are disclosed. Each alignment mark is placed on a pad adjacent to a contact tip. The alignment mark is positioned on the pad so that it will not contact the terminal or any other part of a wafer under test. The alignment mark and the contact tip are
10 preferably positioned on the pad in the same lithographic step. Then, the pad and like pads, selected ones of which also have similar alignment marks, are attached to the ends of an array of resilient contact elements. A plurality of alignment marks in accurate registration with a plurality of contact tips on a contactor is thus disclosed. Configurations for ensuring that the alignment marks remain free of debris and easily
15 located for essentially the entire life of the contactor are disclosed, as are various different exemplary shapes of alignment marks.